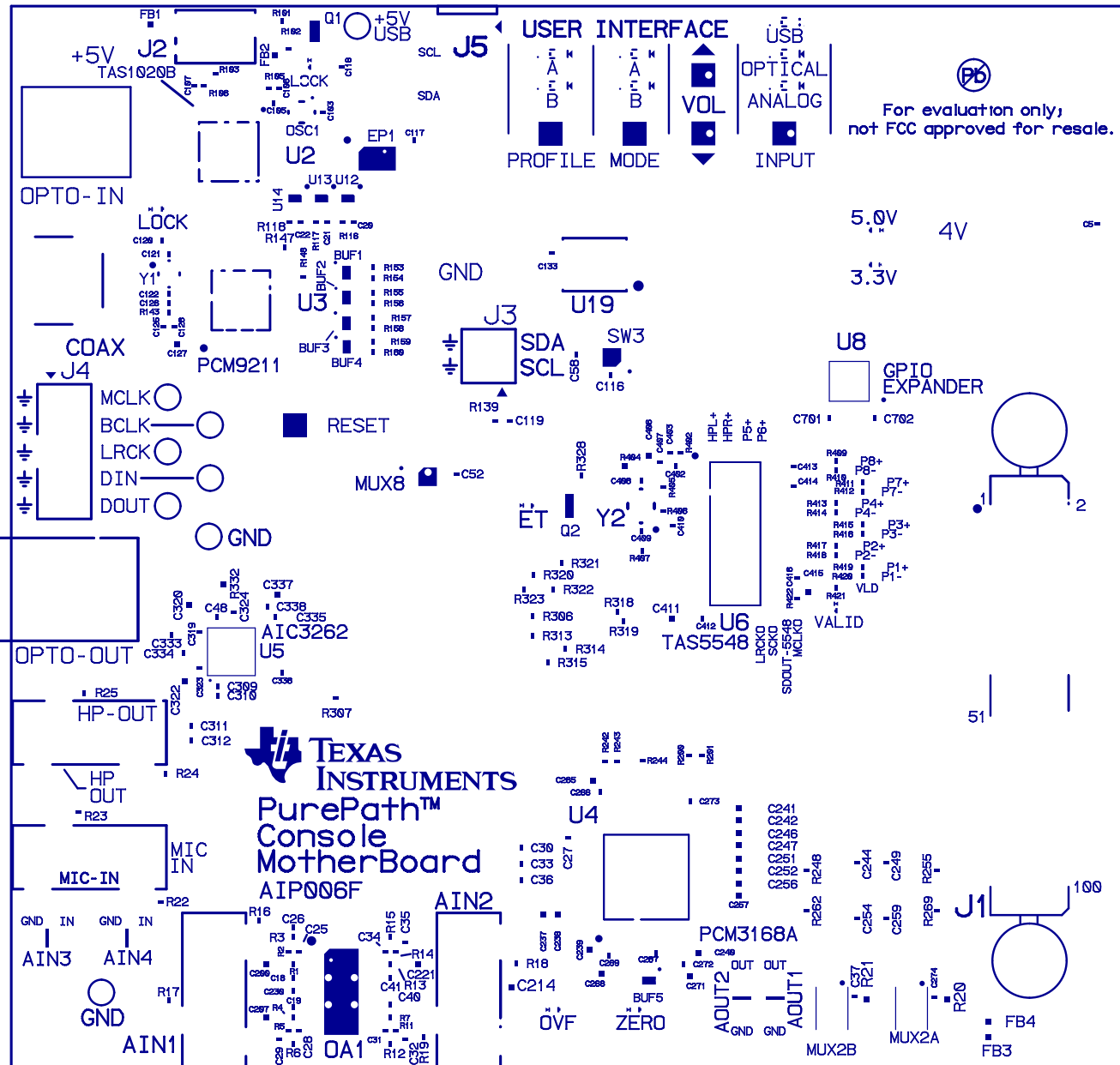




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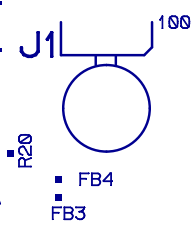


TOP SILKSCREEN

For evaluation only;
not FCC approved for resale.

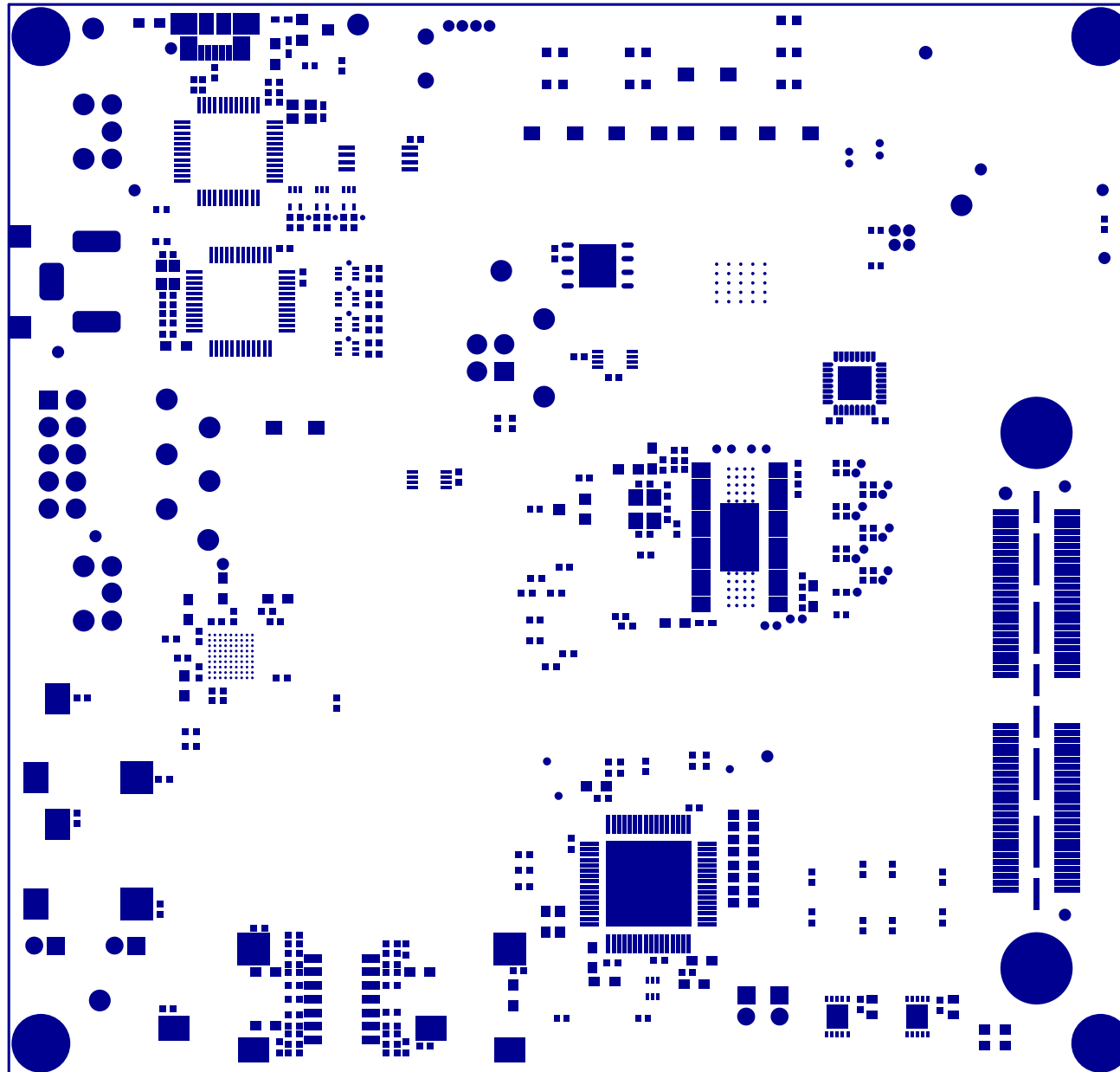
5.0V 4V GND
3.3V

TEXAS INSTRUMENTS
PurePath™
Console
MotherBoard
AIP006F



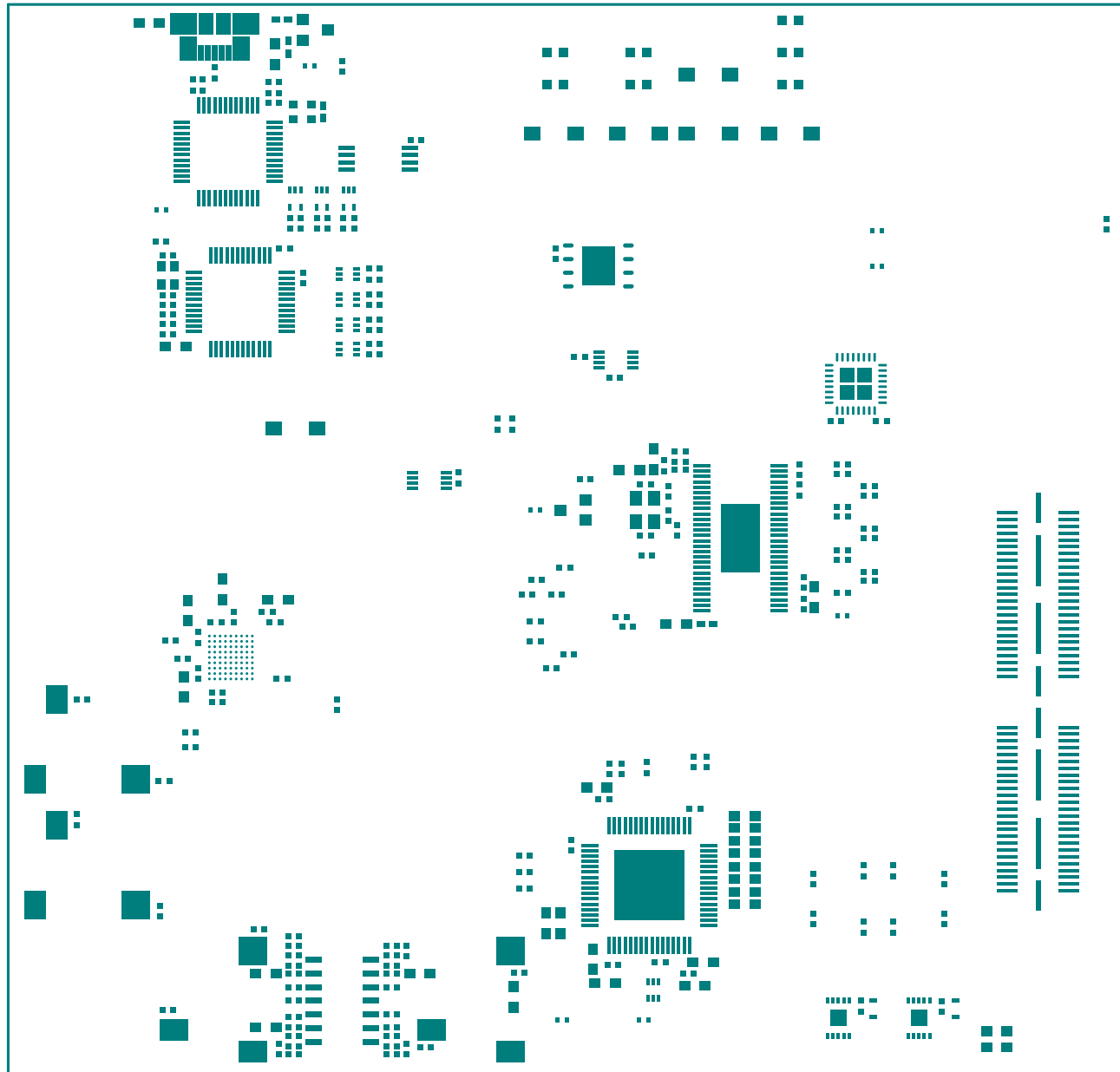


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TOP SOLDERMASK

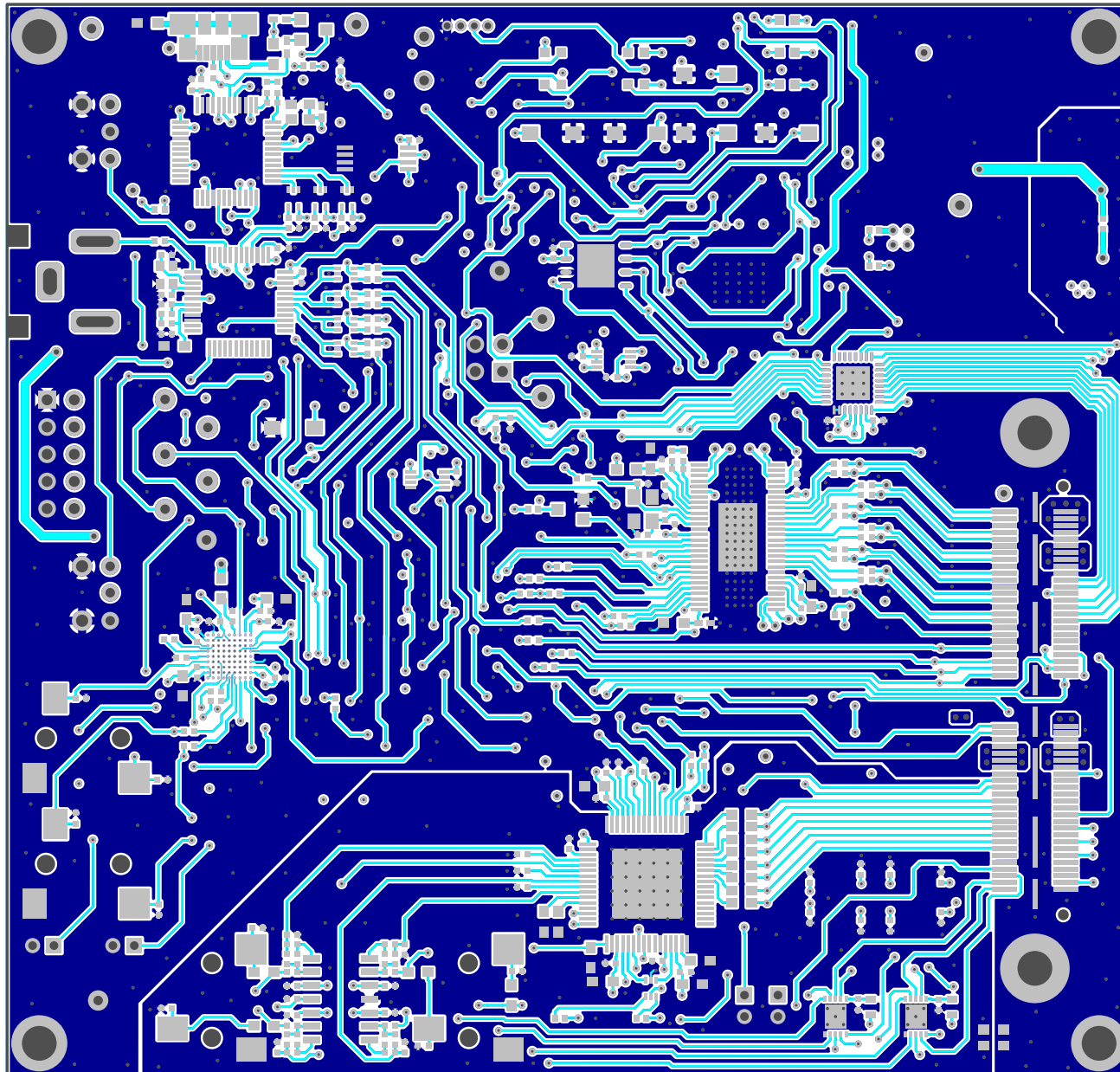
PurePath™ Console MotherBoard AIP006F



TOP SOLDERPASTE



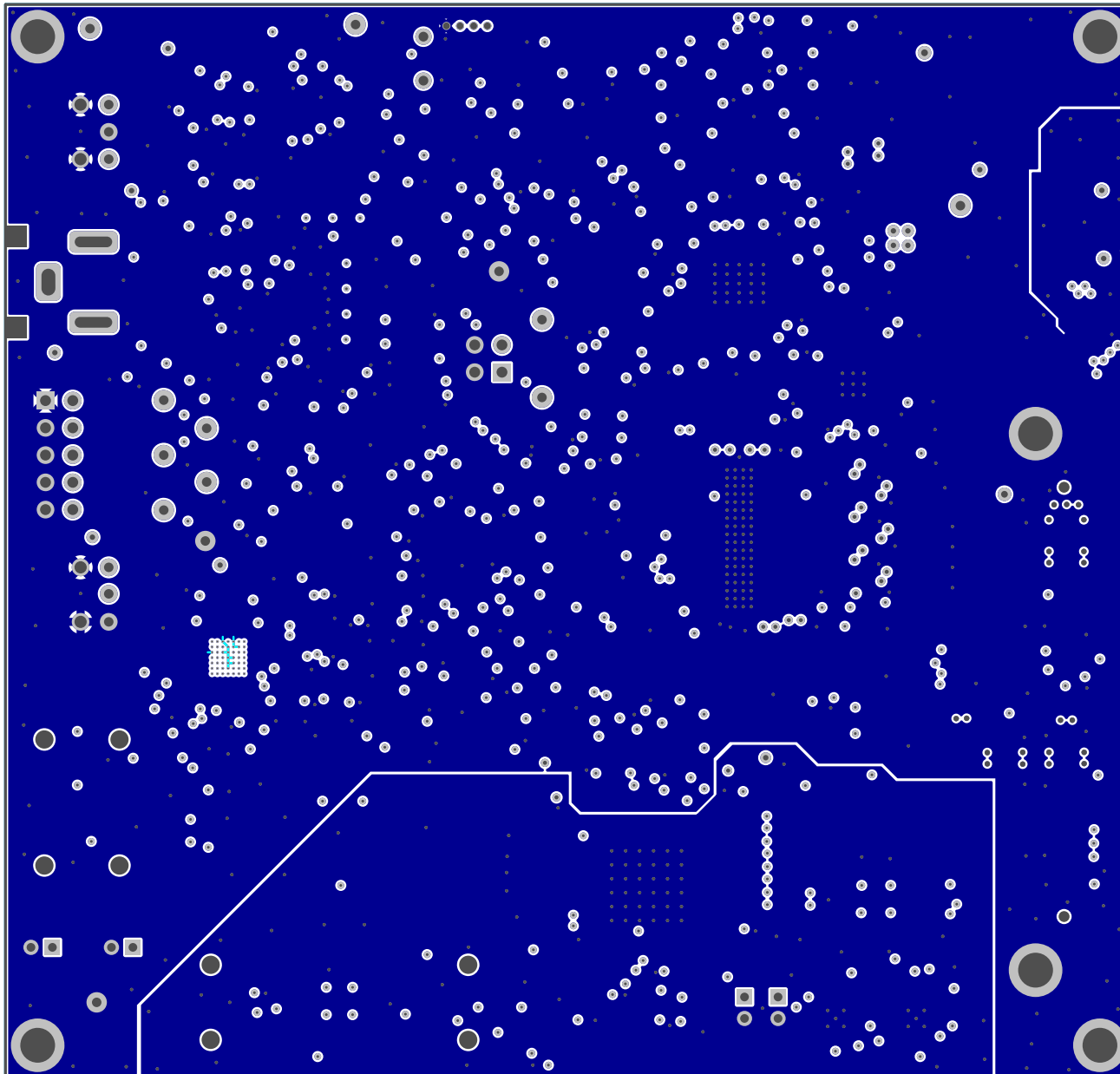
PurePath™ Console MotherBoard AIP006F



TOP COPPER

TOP COPPER ROUTES

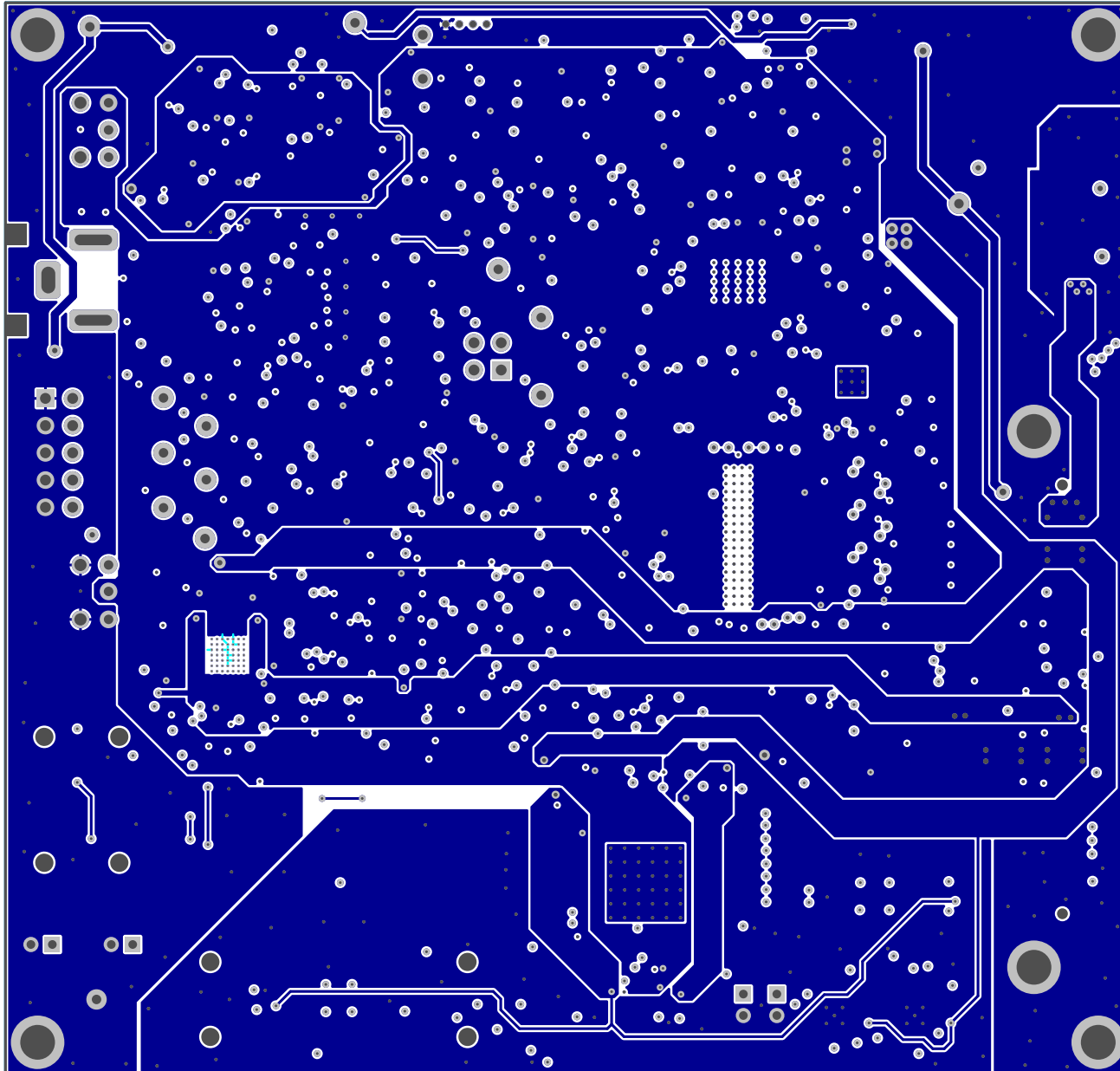
PurePath™ Console MotherBoard AIP006F



COPPER LAYER 2

COPPER LAYER 2 ROUTES

PurePath™ Console MotherBoard AIP006F

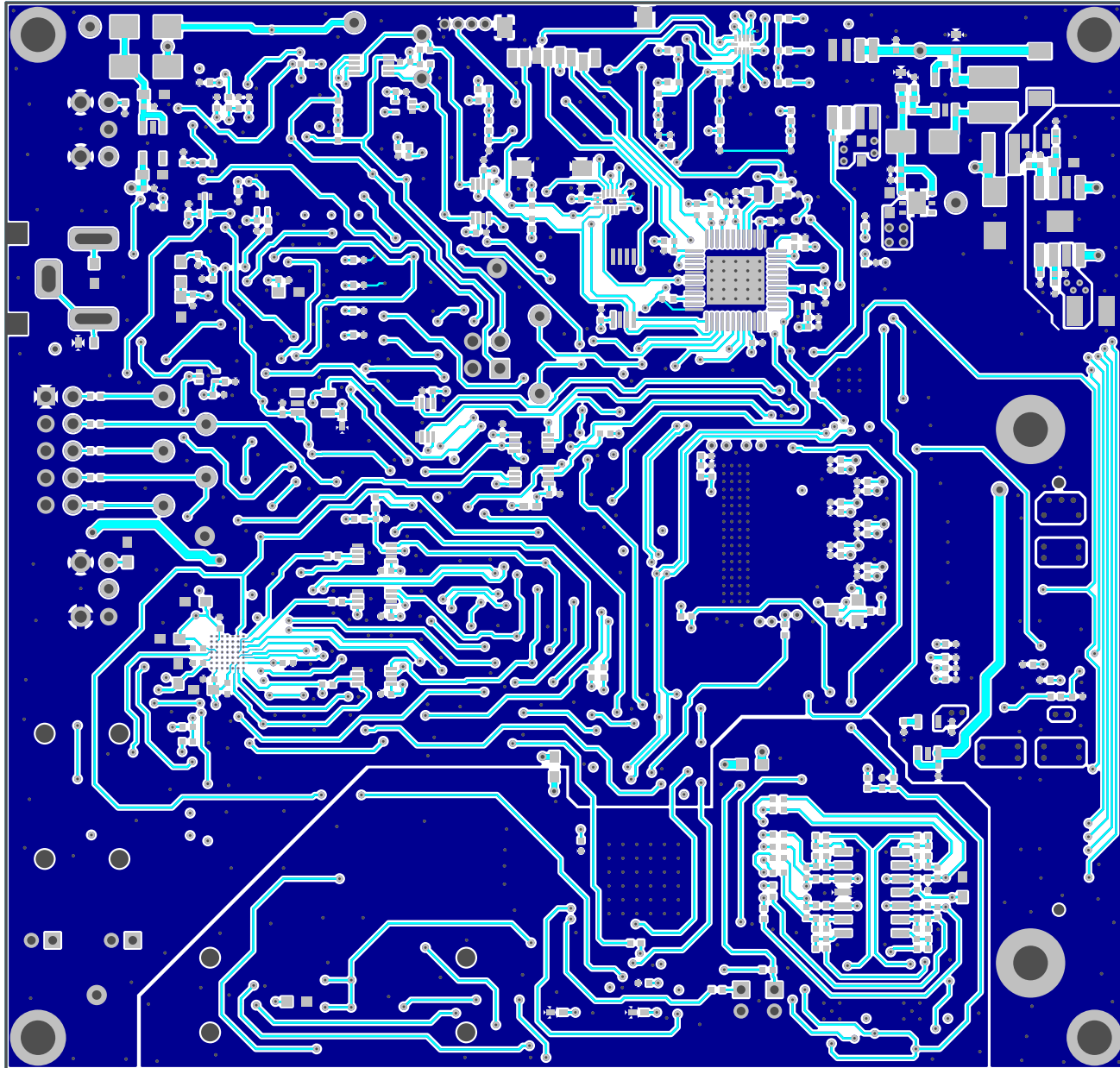


COPPER LAYER 3

COPPER LAYER 3 ROUTES



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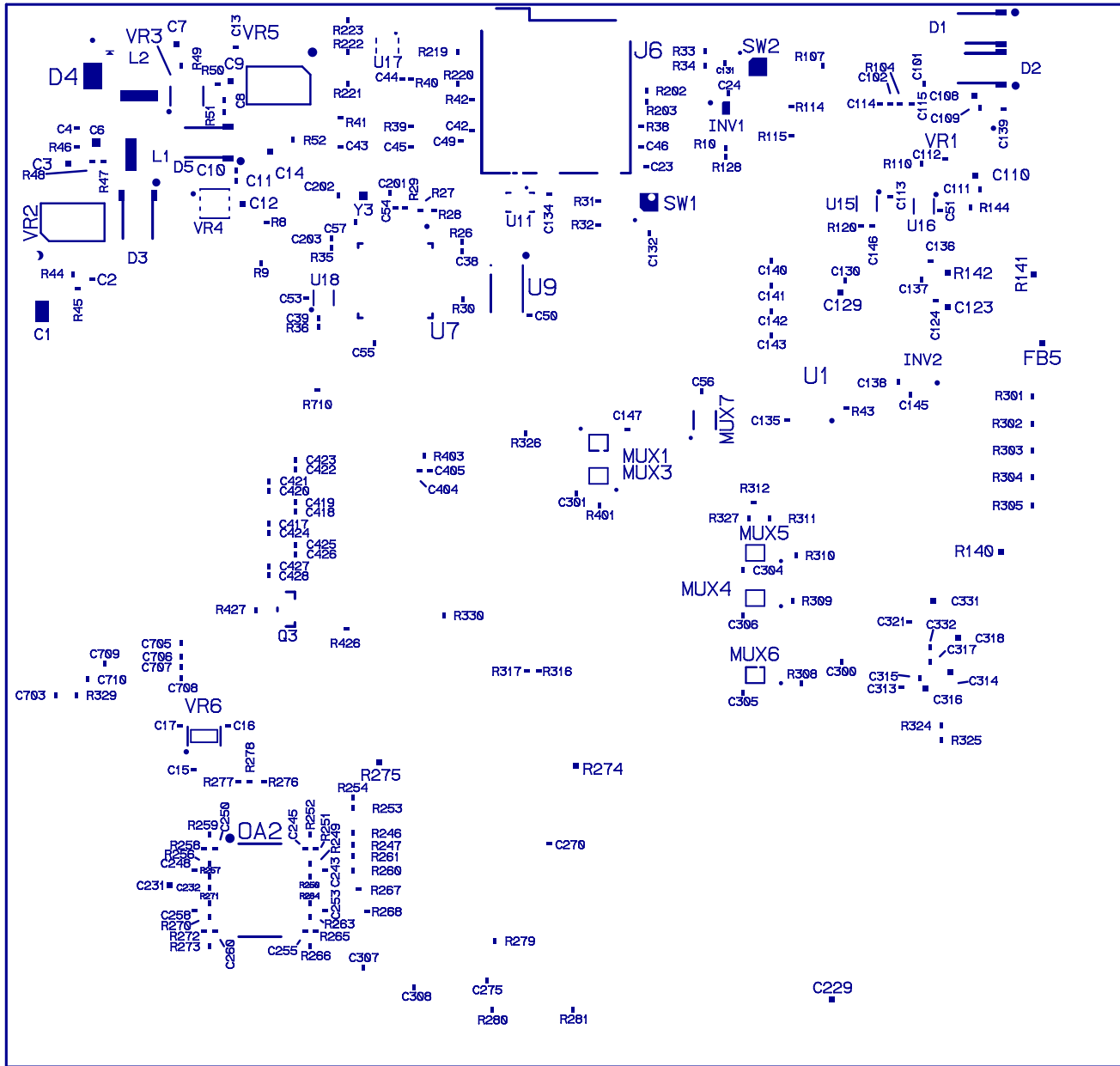


BOTTOM COPPER

BOTTOM COPPER ROUTES



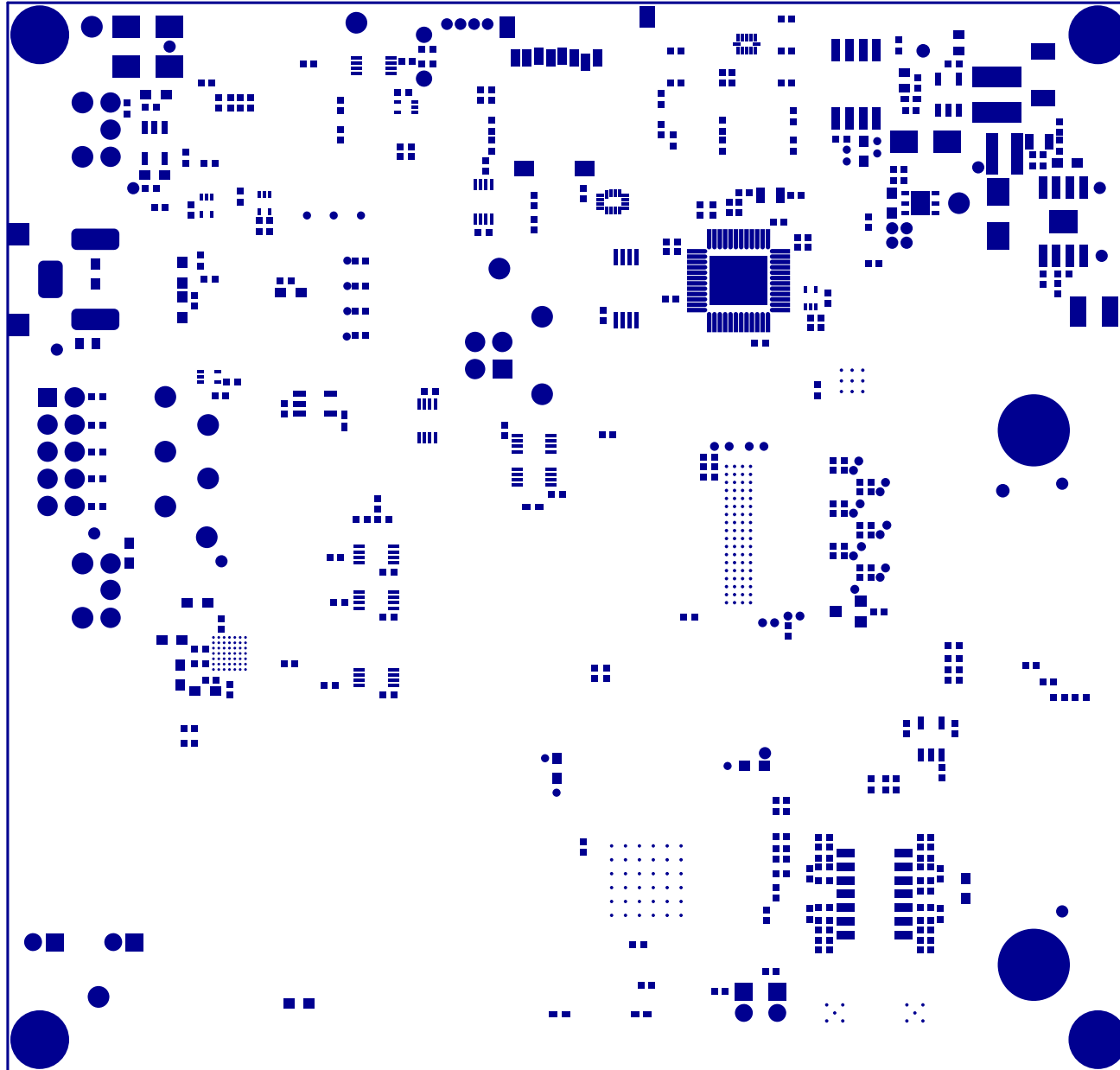
PurePath™ Console MotherBoard AIP006F



BOTTOM SILKSCREEN

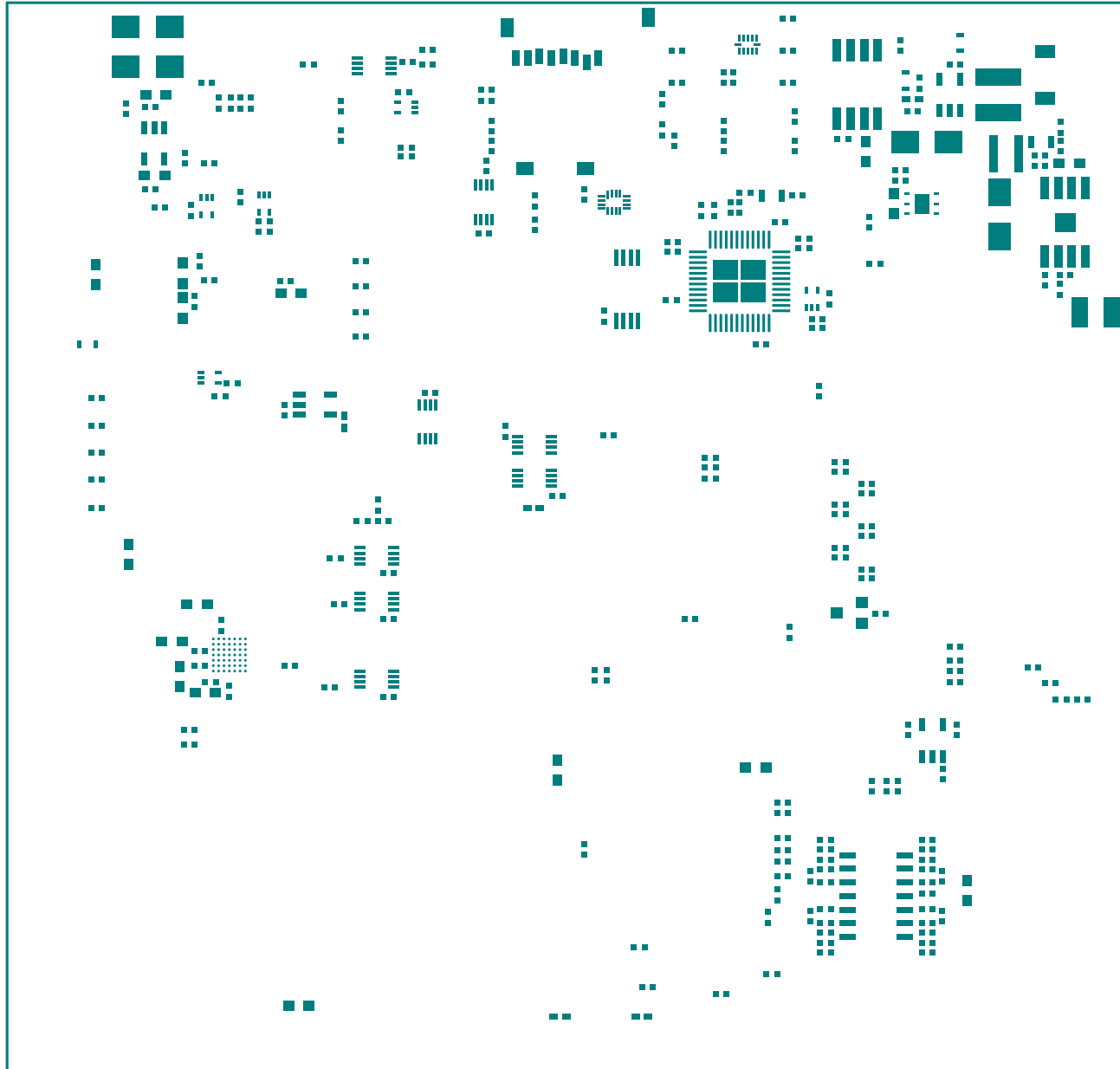


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BOTTOM SOLDERMASK

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BOTTOM SOLDERPASTE

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